



General Description

These N-Channel enhancement mode power field effect transistors are using trench MOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

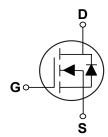
BV _{DSS}	R _{DS(ON)}	I _D
80 V	12 mΩ	82 A

Features

- $\cdot R_{DS(ON)} \le 12m\Omega@V_{GS} = 10V$
- Fast Switching
- · Improved dv/dt Capability
- · Green Device Available

PPAK5X6 Pin Configuration





Applications

- · Synchronous Rectification
- · DC/DC Converter
- Motor Control

Symbol	Parameter	Rating	Units	
V_{DS}	Drain-Source Voltage	80	V	
V_{GS}	Gate-Source Voltage	±20	V	
I _D	Drain Current - Continuous (T _C =25°C)	82	Α	
I _{DM}	Drain Current - Pulsed (NOTE 1)	328	Α	
EAS	Single Pulse Avalanche Energy (NOTE 2)	204.8	mJ	
P_{D}	Power Dissipation (T _C =25°C)	139	W	
T _J	Operating Junction Temperature Range	-55 to 150	°C	
T _{STG}	Storage Temperature Range	-55 to 150	°C	
Marking Code		NK012		

Thermal Characteristics					
Symbol	Rating	Unit			
$R_{\theta JA}$	Thermal Resistance Junction to Ambient	42	°C/W		
$R_{ heta JC}$	Thermal Resistance Junction to Case	0.9	°C/W		





Electrical Characteristics (T_{.1}=25°C, unless otherwise noted)

Off Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	80			V
I _{DSS}	Drain-Source Leakage Current	V_{DS} =80V , V_{GS} =0V			1	uA
I _{GSS}	Gate-Source Leakage Current	V_{GS} =±20V , V_{DS} =0V			±100	nA

On Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =10V , I _D =20A			12	mΩ
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$, $I_D=250uA$	2.0		4.0	V

Dynamic and switching Characteristics

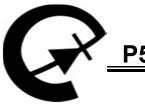
Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Q_g	Total Gate Charge			68.7		
Q_{gs}	Gate-Source Charge	V_{DS} =40V , V_{GS} =10V , I_{D} =20A		16		nC
Q_{gd}	Gate-Drain Charge			22.5		
$T_{d(on)}$	Turn-On Delay Time			35		
T _r	Rise Time	V_{DD} =40V , V_{GS} =10V , R_{G} =4.7 Ω , I_{D} =20A		75		nS
$T_{d(off)}$	Turn-Off Delay Time			90		113
T_f	Fall Time			30		
C _{iss}	Input Capacitance			4150		
C _{oss}	Output Capacitance	V _{DS} =40V , V _{GS} =0V , F=1MHz		220		pF
C_{rss}	Reverse Transfer Capacitance			157		

Drain-Source Diode Characteristics and Ratings

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current	V _G =V _D =0V , Force Current			80	Α
V_{SD}	Diode Forward Voltage	V _{GS} =0V , I _S =1A			1	V

NOTES:

- ${\bf 1.}\ Repetitive\ Rating: Pulsed\ width\ limited\ by\ maximum\ junction\ temperature.$
- 2. V_{DD} =40V, V_{GS} =10V, L=0.4mH, I_{AS} =32A.
- 3. The data tested by pulsed , pulse width \leq 300us , duty cycle \leq 2%.
- 4. Essentially independent of operating temperature.



P5MNK012



80V N-Channel MOSFETs

Characteristics Curves

FIG. 1-Forward Characteristics of Body Diode

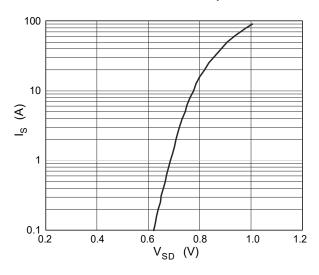


FIG. 2-Power Dissipation

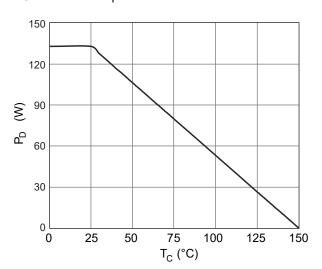


FIG. 2-Normalized $R_{\text{DS}(\text{ON})}\,\text{vs}\;T_{\text{J}}$

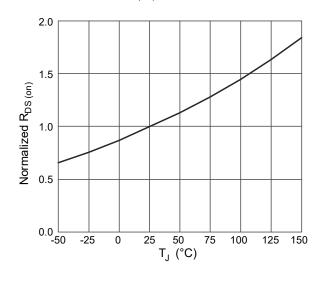


FIG. 4-Gate Charge Characteristics

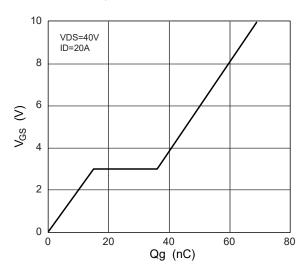


FIG. 5-Safe Operation Area

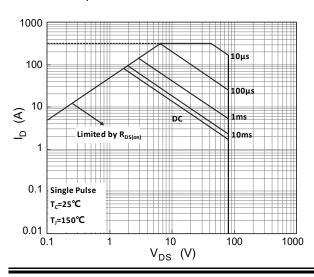
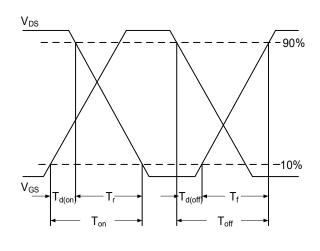


FIG. 6-Switching Time Waveform

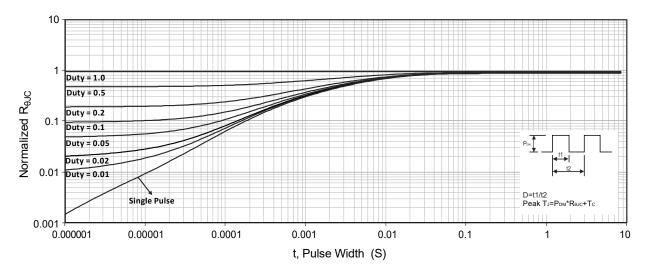




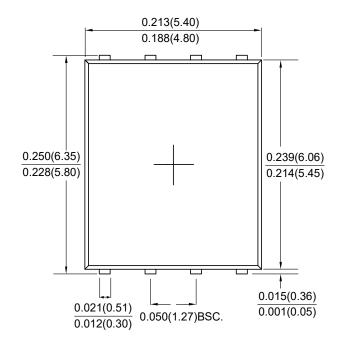


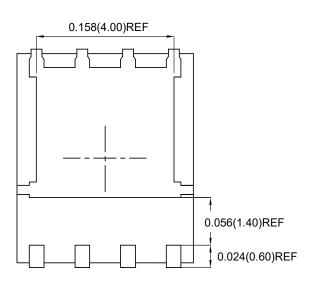
Characteristics Curves

FIG. 7-Normalized Maximum Transient Thermal ImpedanceFigure



Package Outline Dimensions









PPAK5X6

Dimensions in inches and (millimeters)





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